

### DESCRIPTION

The 2301 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

### GENERAL FEATURES

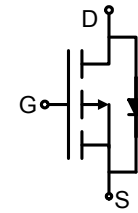
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$V_{DSS}$	$R_{DS(ON)}$ @-4.5V(Typ)	$R_{DS(ON)}$ @-2.5V(Typ)	$I_D$
-20V	64m $\Omega$	89 m $\Omega$	-3A

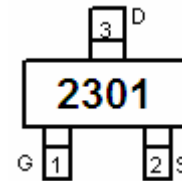
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

### Application

- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	-3	A
Drain Current -Pulsed (Note 1)	$I_{DM}$	-10	A
Maximum Power Dissipation	$P_D$	1	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	125	°C/W
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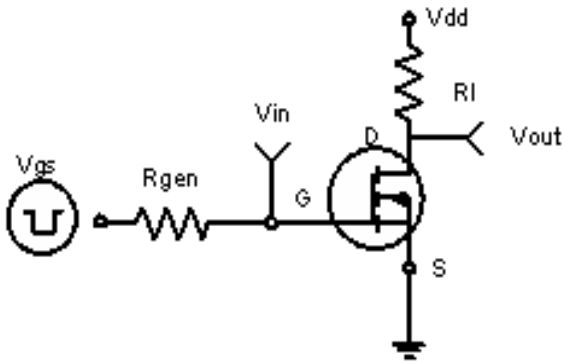
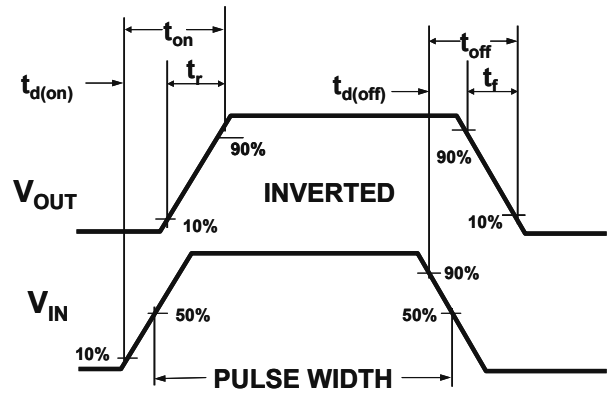
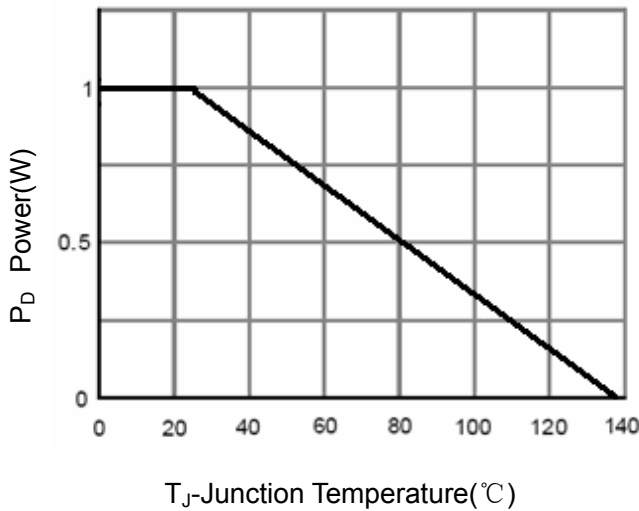
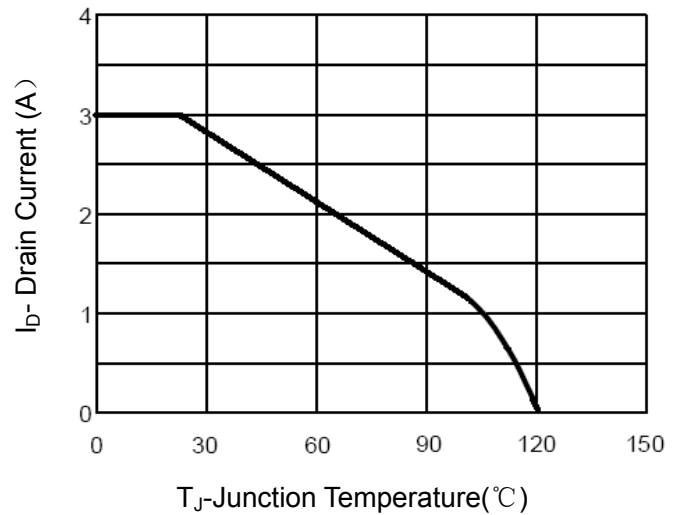
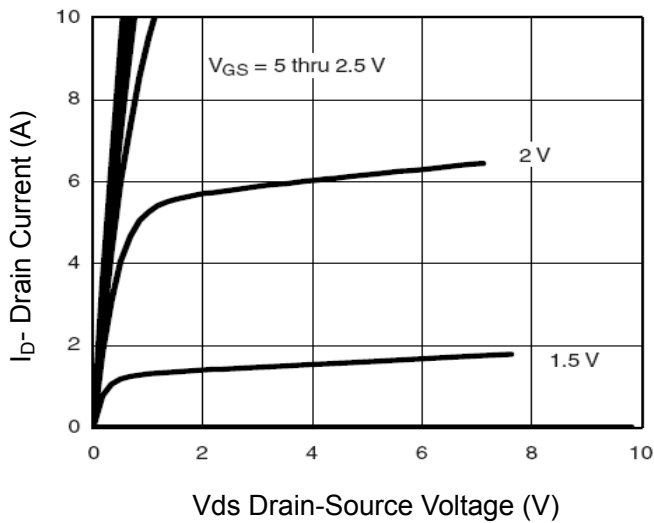
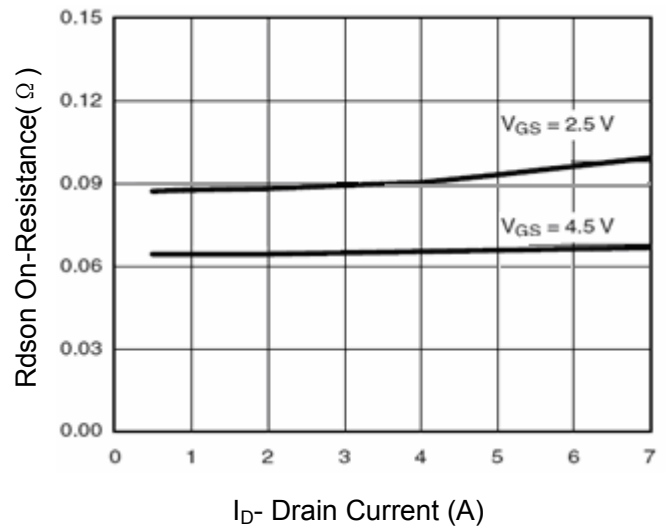
### Electrical Characteristics (TA=25°C unless otherwise noted)

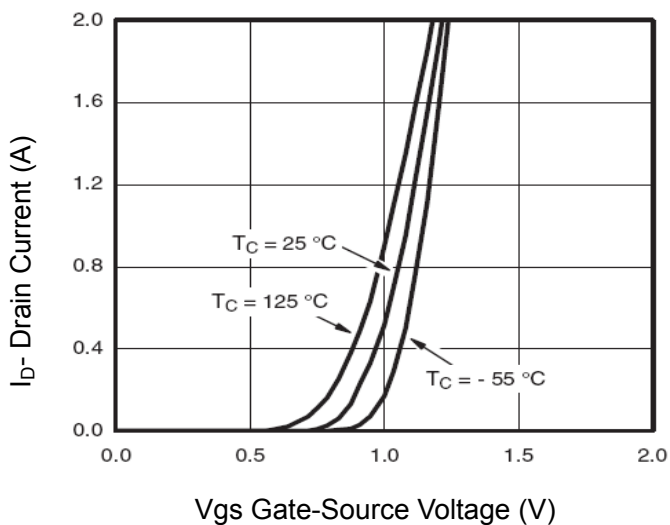
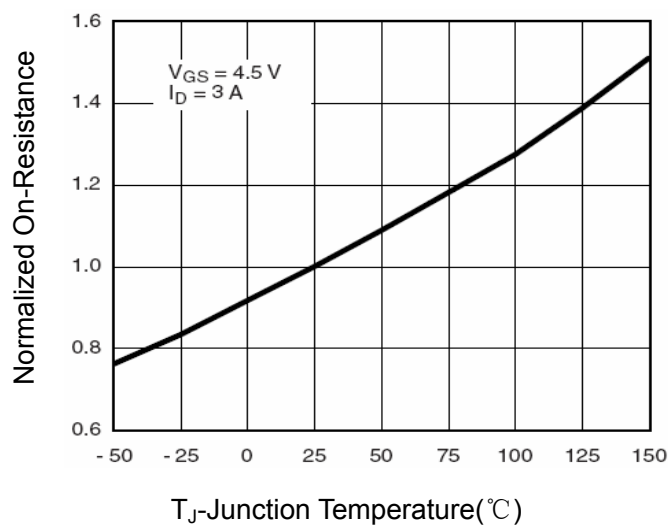
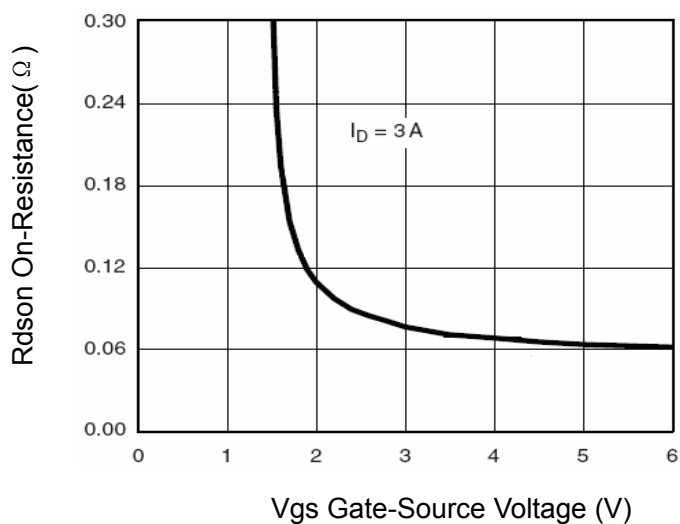
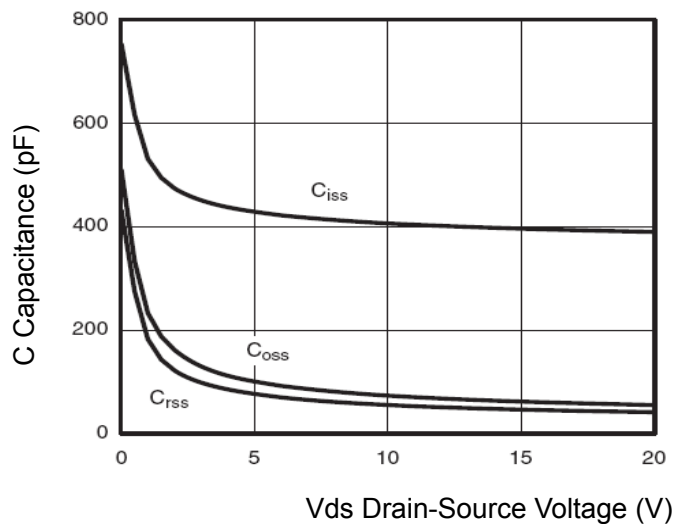
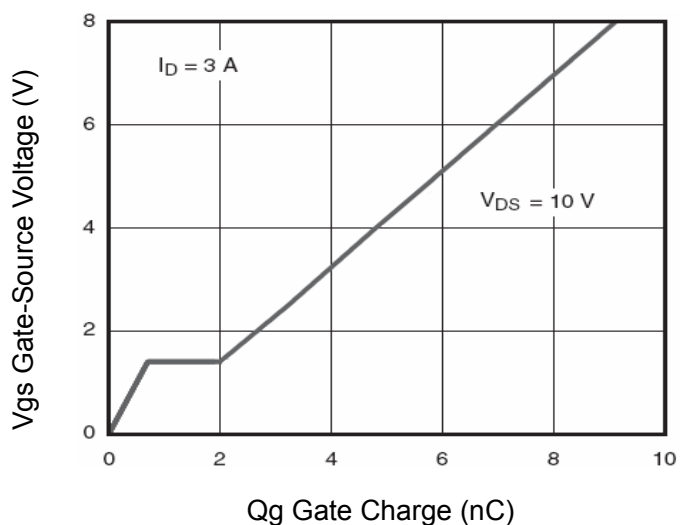
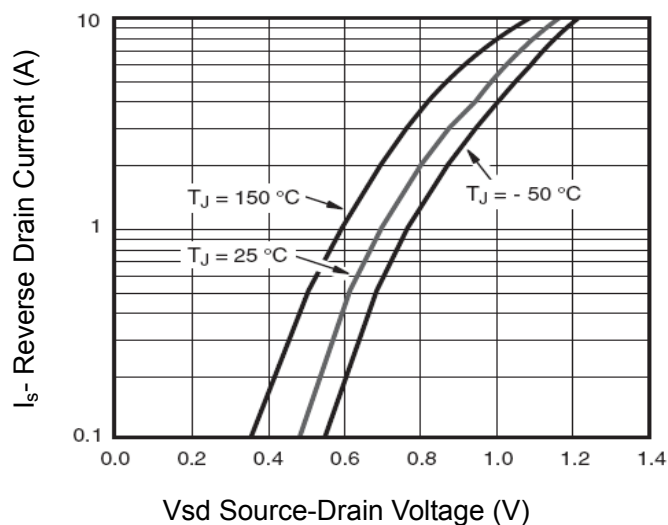
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20	-24	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V$	-	-	-1	$\mu A$

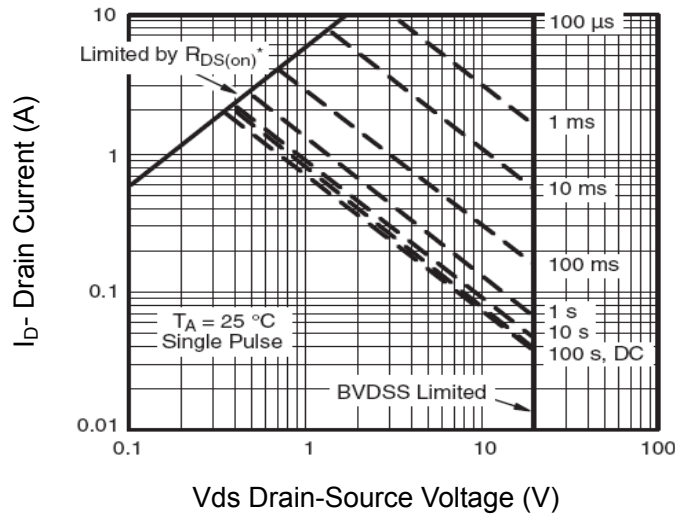
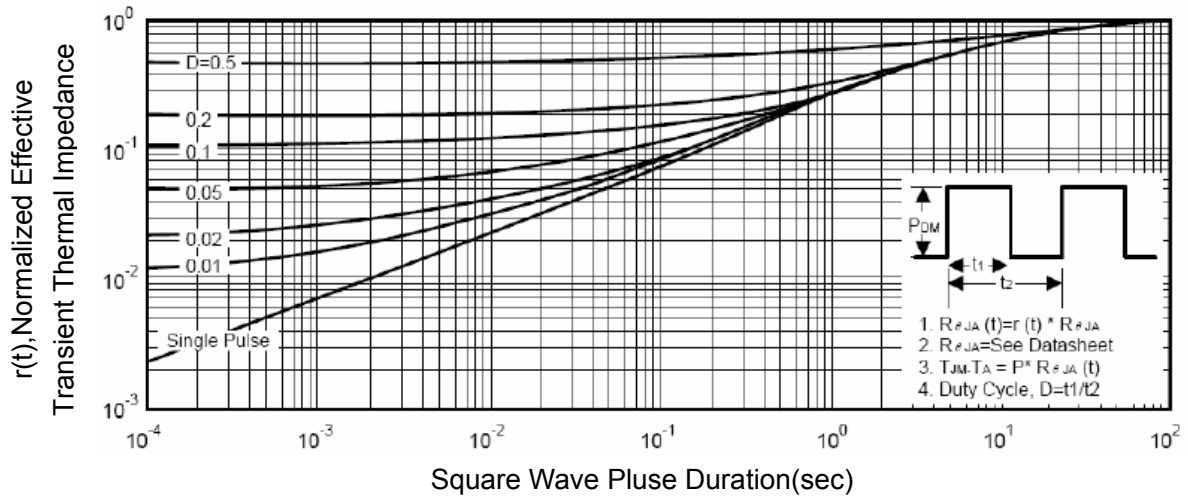
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-3A$	-	64	110	m $\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	-	89	140	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-5V, I_D=-2.8A$	-	9.5	-	S
<b>Dynamic Characteristics (Note4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V,$ $F=1.0MHz$	-	405	-	PF
Output Capacitance	$C_{oss}$		-	75	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	55	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10V, I_D=-1A$ $V_{GS}=-4.5V, R_{GEN}=10\Omega$	-	11	-	nS
Turn-on Rise Time	$t_r$		-	35	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	$t_f$		-	10	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-10V, I_D=-3A,$ $V_{GS}=-2.5V$	-	3.3	12	nC
Gate-Source Charge	$Q_{gs}$		-	0.7	-	nC
Gate-Drain Charge	$Q_{gd}$		-	1.3	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=1.3A$	-	-	-1.2	V
Diode Forward Current (Note 2)	$I_S$		-	-	-1.3	A

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 1: Switching Test Circuit**

**Figure 2: Switching Waveforms**

**Figure 3 Power Dissipation**

**Figure 4 Drain Current**

**Figure 5 Output CHARACTERISTICS**

**Figure 6 Drain-Source On-Resistance**


**Figure 7 Transfer Characteristics**

**Figure 8 Drain-Source On-Resistance**

**Figure 9 Rdson vs Vgs**

**Figure 10 Capacitance vs Vds**

**Figure 11 Gate Charge**

**Figure 12 Source- Drain Diode Forward**


**Figure 13 Safe Operation Area**

**Figure 14 Normalized Maximum Transient Thermal Impedance**